New Configurations for RF/Microwave Filters

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Outline

- Introduction
- Conventional Filter Theory
- Need for Folded Transmission Lines
- Single-level Folded line Bandstop and Lowpass Filters
- Multi-level Folded line Bandstop and Lowpass Filters
- Advantages of Folded Line Filters
- Conclusions



Introduction

- The explosive growth in miniature wireless communication hardware drives the need for miniaturization
- Increasing role of embedded passives
- Off-chip and On-chip applications
- Novel filter configurations desired
- Focus on Bandstop and Lowpass filters



Typical Receiver Architecture

Antenna





Conventional Design Methodology: Limiting Factors

- < 1 GHz Typically Lumped Configurations
- > 10 GHz Typically Distributed Configurations
- Lower RF, microwave frequencies (1-10 GHz)
- Large component footprints
- ♦ Stub loaded filters → extremely narrow or wide line
 widths → impractical for physical implementation



Folded Filter Methodology

- Folding the transmission lines yields a more compact footprint
- Common design methodology for both bandstop and lowpass filters
- Conventional filter theory still applicable in the first phase of the design



Folded Line Examples



Network Representation for Single Level Folded Line Filters

• 2N×2N port network

 $\begin{bmatrix} Y \end{bmatrix} = \begin{bmatrix} Y_A & Y_B \\ Y_B & Y_A \end{bmatrix}$

 $[Y_{A}] = [M_{v}]^{T} [\operatorname{coth}(\gamma_{k}l)]_{diag} [Y_{k}]_{diag} [M_{v}]^{-1}$

$$\begin{bmatrix} Y_B \end{bmatrix} = \begin{bmatrix} M_v \end{bmatrix}^T \begin{bmatrix} \operatorname{csch}(\gamma_k l) \end{bmatrix}_{diag} \begin{bmatrix} Y_k \end{bmatrix}_{diag} \begin{bmatrix} M_v \end{bmatrix}^{-1}$$
$$\begin{bmatrix} Y_k \end{bmatrix} \approx \begin{bmatrix} M_v \end{bmatrix}^{-1} \begin{bmatrix} Y_{SH} \end{bmatrix} \begin{bmatrix} M_v \end{bmatrix}$$

 $[Y_{SH}] = [G] + j\omega[C]; [Z_S] = [R] + j\omega[L]$

V₁ Sub N.W Sub N.W Sub transmission lines S_{2Nx2N} Sub N.W Sub N.W Sub N.W

Reduced 2-port scattering matrix



Folded Line Filter Section





Filter Design Procedure





Single Level Folded Line Bandstop Filters (Example #1)

- Initial design of stubloaded bandstop filter
- Specifications
- > N=3, f₀=1.5 GHz
- Maximally flat amplitude response (Butterworth)
- > ∆=0.2 & 0.3
- Microstrip realization
 ε_r=2.2, h=31mil

• Design equations for N=3

$$\begin{split} &Z_1 = Z_A (1 + 1/\Lambda g_0 g_1) \ Z_{12} = Z_A (1 + \Lambda g_0 g_1) \\ &Z_2 = Z_A g_0 / \Lambda g_2 \qquad Z_3 = Z_A g_0 / g_4 (1 + 1/\Lambda g_3 g_4) \\ &Z_{23} = Z_A g_0 / g_4 (1 + \Lambda g_3 g_4) \\ &Z_A \text{ and } Z_B = \text{ terminating impedances} \\ &Z_j \ (j = 1 \text{ to } n) = \text{OC shunt stub impedances} \\ &Z_{1j} \ (j = 2 \text{ to } n) = \text{connecting line impedances} \\ &g_j = \text{ prototype element values} \end{split}$$

$$\Lambda = \omega_0 a, \quad a = \cot(\frac{\pi}{2} \ \frac{\omega_1}{\omega_0})$$
$$\Delta = \frac{\omega_2 - \omega_1}{\omega_0}, \quad \omega_0 = \frac{\omega_1 + \omega_2}{2}$$

 ω_1 and $\omega_2 =$ bandstop edge frequencies



Characteristic Impedances for Various Bandstop Filter Sections

Δ	Ζ _Α (Ω)	Z ₁ (Ω)	Z ₁₂ (Ω)	Ζ ₂ (Ω)	Z ₂₃ (Ω)	Ζ ₃ (Ω)	Ζ _B (Ω)
0.3	50	258	62	104	62	258	50
0.2	50	365.7	57.9	157.8	57.9	365.7	50

N=3, Maximally flat response , f_0 =1.5 GHz

50Ω microstrip line \rightarrow w = 98 mil

365.7 Ω microstrip line \rightarrow w = 0.1 mil

258 Ω microstrip line \rightarrow w = 1 mil

(1/2 ounce copper, 0.7 mil)



Design Flow for the Folded Line Bandstop Filters (Single-Level)



Bandstop Filter Comparison (Δ = 0.2)



- Microstrip realization
- $\geq \epsilon_r$ =2.2, h=31mil
- Conventional stub-loaded filter measured 2948 sq mm
- Folded line filter measured 767 sq mm !!
- Please note the 'aspect ratio' for conventional -> printing artifact ->line widths are too small to be shown accurately



Footprint & Critical Conductor Width Comparison

Δ=0.2	Conventional Bandstop	Folded line Bandstop	
Smallest normalized width (w/h)	0.0032 (0.099 mil)	0.26 (8.06 mil)	
Overall footprint	2948 sq mm	767 sq mm	
Footprint comparison	100 %	26 %	



Filter Response



- \square S₁₁(Conventional filter theoretical) \square S₂₁(Conventional filter theoretical)
- S₁₁(Folded filter theoretical)
- S₁₁(Folded filter MWS 2006®)
- S₂₁(Folded filter theoretical)
- S₂₁(Folded filter MWS 2006®)



Bandstop Filter Comparison (Δ = 0.3)



- Microstrip realization
- $\geq \epsilon_r$ =2.2, h=31mil
- Conventional stub-loaded filter measured 2948 sq mm
- Folded line filter measured 1015 sq mm !!
- Please note the 'aspect ratio' for conventional -> printing artifact ->line widths are too small to be shown accurately_{cst}



Footprint & Critical Conductor Width Comparison

Δ=0.3	Conventional Bandstop	Folded line Bandstop	
Smallest normalized width (w/h)	0.032 (0.99 mil)	0.5 (15.5 mil)	
Overall footprint	2948 sq mm	1015 sq mm	
Footprint comparison	100 %	34 %	



Fabricated Folded Line Bandstop Filter





RT Duroid 5880



Folded Line Bandstop Filter Response





Folded Line Bandstop Filter Response (Cont'd)





Folded Line Bandstop Filter Response (Cont'd)





Re-entry characteristics similar to conventional filters but higher frequencies are shifted due to increased coupling.



Folded Line Bandstop Filter Response (Cont'd)





Re-entry characteristics similar to conventional filters but higher frequencies are shifted due to increased coupling.



Single Level Folded Line Lowpass Filters (Example #2)

- Initial design of stubloaded lowpass filter
- Specifications
- ≻ N=3, f_c=1.5 GHz
- Maximally flat response (Butterworth)
- Microstrip platform
- $\geq \epsilon_r$ =2.2, h=31mil

- Lumped-element prototype
- Richard's transformations
- Unit elements
- Kuroda's identities
- Impedance scaling
- Frequency scaling

 $Z_{\rm A}$ and $Z_{\rm B}~$ = Terminating impedances

 Z_j (j =1 to n) = OC shunt stub impedances

 $Z_{1j} \ (j \ = 2 \ to \ n)$ = Connecting line impedances



Characteristic Impedances for Various Lowpass Filter Sections

Z _A (Ω)	Z ₁ (Ω)	Z ₁₂ (Ω)	Z ₂ (Ω)	Z ₂₃ (Ω)	Z ₃ (Ω)	$Z_{B}(\Omega)$
50	100	100	25	100	100	50

N=3,Maximally flat response , f_c=1.5 GHz

50Ω microstrip line \rightarrow w = 98 mil

25 Ω microstrip line \rightarrow w =243 mil (6.17 mm)

(1/2 ounce copper, 0.7 mil)



Design Flow for the Folded Line Lowpass Filters (Single-Level)



Lowpass Filter Comparison



- Microstrip realization
- ε_r=2.2, h=31mil
- Conventional stub-loaded filter measured 755 sq mm
- Folded line filter measured 535 sq mm !!



Footprint & Critical Conductor Width Comparison

f _c =1.5 GHz	Conventional Lowpass	Folded line Lowpass	
Largest normalized width (w/h)	7.9 (244.9 mil)	3.63 (112.5 mil)	
Overall footprint	755 sq mm	535 sq mm	
Footprint comparison	100 %	71 %	



Fabricated Folded Line Lowpass Filter









Folded Line Lowpass Filter Response





Folded Line Lowpass Filter Response (Cont'd)







Importance of the Ground Plane (BTB Microstrip Realization)

- Isolates the top and bottom metallization layers
- More practical via dimensions
- Less prone to alignment errors



A Back-to-Back Microstrip Geometry





Network Representation for Multi Level Folded Line Filters



- 2N x 2N port networks
- Cascade of three separate networks
- Reduced 2-port scattering matrix



Composite Geometry



3D View

Overhead View



Via Model Extraction



Closed form design equations

L(w)= 0.5054*exp(-1.7014*w^{0.8846})+ 0.4298 nH

C(w)= 0.2209*exp(0.2564*w^{0.9555}) - 0.1918 pF

R(w)= -0.0026*exp(1.6083*w^{0.5072}) + 0.0911 Ω

Diameter of the via = $\frac{1}{2}$ width of the strip Diameter of the antipad = 0.4 mm + diameter of the via



Via R, L, C Vs. Line Width





Design Procedure for Multilevel Bandstop and Lowpass Filters





Multi Level Folded Line Bandstop Filters (Example #3)

- Initial design specifications of stub-loaded bandstop filter
- ➢ N=3, f₀=1.5 GHz
- Maximally flat response (Butterworth)
- ≻ ∆=0.3
- BTB microstrip realization
- $\geq \epsilon_r$ =2.2, h=31mil for both dielectric layers





- BTB microstrip platform
- > ϵ_r =2.2,h=31mil for both dielectric layers
- Conventional stub-loaded filter measured 2948 sq mm
- Folded line filter measured 532 sq mm !!



3D View of the Multilevel Folded Line Bandstop Filter



Ground plane and dielectrics are hidden for better visibility



Footprint & Critical Conductor Width Comparison

	Conventional	Single Level	Multi Level
Δ=0.3	Bandstop	Folded Line	Folded Line
		Bandstop	Bandstop
Smallest normalized width (w/h)	0.032 (0.99 mil)	0.5 (15.5 mil)	0.4 (12.4 mil)
Overall footprint	2948 sq mm	1015 sq mm	532 sq mm
Footprint comparison	100 %	34 %	18 %



Fabricated Folded Line Bandstop Filter

Top metallization layer



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Bottom metallization layer



Folded Line Bandstop Filter Response





Folded Line Bandstop Filter Response (Cont'd)





Multi Level Folded Line Lowpass Filters (Example #4)

- Initial design specifications of stub-loaded lowpass filter
 N=3, f_c=1.5 GHz
- Maximally flat response (Butterworth)
- BTB microstrip platform
- > ϵ_r =2.2, h=31mil for both dielectric layers





- BTB microstrip realization
- $\geq \epsilon_r = 2.2$, h=31mil for both dielectric layers
- Conventional stub-loaded filter measured 755 sq mm
- Folded line filter measured 235 sq mm !!



3D View of the Multilevel Folded Line Lowpass Filter



Ground plane and dielectrics are hidden for better visibility



Footprint & Critical Conductor Width Comparison

f _c =1.5 GHz	Conventional Lowpass	Single Level Folded Line Lowpass	Multi Level Folded Line Lowpass
Largest normalized width (w/h)	7.9 (244.9 mil)	3.63 (112.5 mil)	3.21 (99.5 mil)
Overall footprint	755 sq mm	535 sq mm	235 sq mm
Footprint comparison	100 %	71 %	31 %



Fabricated Folded Line Lowpass Filter

Top metallization layer





Bottom metallization layer



BTB Microstrip Realization



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Folded Line Lowpass Filter Response





Folded Line Lowpass Filter Response (Cont'd)





Advantage Summary of Folded Topologies

- Uses a common design methodology for both bandstop and lowpass filters
- More compact footprints than conventional
- More feasible physical dimensions (i.e. aspect ratio) for a practical implementation
- Embedded ground plane aids in the design of multi level filters
- Equivalent electrical performance to that of the conventional filters
- Host of embedded passive and RFIC applications in the 1-10 GHz range

